

ABSTRACT

Provided is a copper foil comprising an electric resistive film layer, wherein a copper-zinc alloy layer in which the zinc content per unit area is 1000 to 9000 $\mu\text{g}/\text{dm}^2$ is formed on a roughened or a gloss surface of a copper foil, a stabilization layer having a thickness of 5 $\text{\AA}$ to 100 $\text{\AA}$ formed from at least one component selected from zinc oxide, chromic oxide, and nickel oxide is formed on the copper-zinc alloy layer, and a film layer formed from an electric resistive material is formed on the stabilization layer. As a result of additionally forming an electric resistive film layer on the copper foil, the provided copper foil with an electric resistive film layer enables the resistor to be built into the substrate as well as improving the adhesiveness thereof.

Fig. 2